

## SUPPLEMENTAL APPLICATION DATA SHEET

The information shown below supercedes and replaces that originally given on the Application Data Sheet filed with this application on July 23, 2001.

### Inventor Information

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### Application Information:

Title Line One:: MEDIUM AND LOW DENSITY GENE CHIPS  
Title Line Two::  
Title Line Three::  
Total Drawing Sheets:: 2  
Formal Drawings?: No  
Application Type:: Utility  
Docket Number:: JNB 100  
Licensed US Govt. Agency::  
Contract or Grant Numbers One::  
Contract or Grant Numbers Two::  
Secrecy Order in Parent Appl.?: No  
  
Assignee:: Jiangnan Biotech Ltd.  
State of Incorporation:: China

U.S.S.N. 09/912,673  
Filed: July 23, 2001  
Supplemental Application Data Sheet

### **Representative Information**

Representative Customer Number:: 23579

### **Prior Foreign Applications**

Foreign Application One:: 001044958  
Filing Date:: July 23, 2000  
Country:: China  
Priority Claimed:: Yes

ATL1 #571450 v1